



# Japan Regional Standards Committee (JRSC)

Liaison Report

March 2025

**STANDARDS**

CONNECT - COLLABORATE. - INNOVATE. - GROW. - PROSPER

# General Information

- Meetings
  - Previous Meeting: Monday, December 15, 2025 (in the week of SEMICON Japan 2025)
  - Next Meeting: Thursday, April 16, 2026
- Leadership
  - Co-chairs
    - Ryuji Takeda (GlobalWafers Japan)
    - Daisuke Sado (Eagle Industry)
  - Vice Chair
    - Supika Mashiro (Tokyo Electron)

# Topics

# SEMI Standards Awards at SEMICON Japan 2025

## SEMI Japan International Collaboration Award

★ **Hirokazu TSUNOBUCHI** GENETEC CORPORATION  
Traceability Japan TC Chapter

★ **Haruna HAYASHI** Tokyo Electron Limited  
Traceability Japan TC Chapter

They demonstrated outstanding leadership in developing the New Standard, Specification for Traceability Identification Label of Component Parts, through strong international collaboration. This achievement lays the foundation for future standards, greatly contributing to quality improvement and supply chain transparency across the industry. In appreciation of these significant contributions, we are pleased to present the International Collaboration Award.



## SEMI Japan Honor Award

★ **Tetsuya NAKAI** SUMCO CORPORATION  
Silicon Wafer Japan TC Chapter

He has devoted more than 15 years to serving as Co-chair of the Technical Committee, as well as leading multiple Task Forces. Throughout this time, he actively addressed a variety of challenges, played a key role in publishing numerous standards, and greatly increased Japan's influence in the field. In appreciation of these dedicated contributions and outstanding accomplishments, we are pleased to present the Honor Award.

## SEMI Japan Special Award

★ **Masanori YOSHISE**  
Silicon Wafer Japan TC Chapter

As Co-leader of the International Advanced Wafer Geometry (AWG) Task Force for many years, he has played a key role in sharing Japan's remarkable expertise with the international community and has greatly contributed to developing and updating standards. In recognition of his leadership in global collaboration and commitment to standardization, we are honored to present him with this Special Award.

# Technical Committee Awards

<b>3D Packaging &amp; Integration</b> ★ <b>Fumihiko INOUE</b> YOKOHAMA National University	<b>Automation Technology</b> ★ <b>Takeo YAMAKI</b> Yokogawa Digital Corporation	<b>Information &amp; Control</b> ★ <b>Mitsuhiko MATSUDA</b> KOKUSAI ELECTRIC CORPORATION ★ <b>Osamu OHISHI</b> IBM Japan Digital Services Company	<b>Physical Interfaces &amp; Carriers</b> ★ <b>Shoji KOMATSU</b> Acteon NEXT LLC ★ <b>Stefan RADLOFF</b> Intel Corporation
<b>Compound Semiconductor Materials</b> ★ <b>Makoto KITABATAKE</b> ★ <b>Masanori YOSHISE</b>	<b>Facilities</b> ★ <b>Haruna HAYASHI</b> Tokyo Electron Limited	<b>Silicon Wafer</b> ★ <b>Naoyuki J. KAWAI</b> Japan Society of Newer Metals ★ <b>Hirofumi OKANO</b> GlobalWafers Japan Co., Ltd. ★ <b>Hidetoshi TSUNAKI</b> Kobelco Research Institute, Inc.	<b>Traceability</b> ★ <b>Haruna HAYASHI</b> Tokyo Electron Limited
<b>Flexible Hybrid Electronics</b> ★ <b>Hideki IKEDA</b> KOMORI CORPORATION ★ <b>Manabu ITO</b> TOPPAN Holdings Inc. ★ <b>Takanobu NAKAGAWA</b> Innolux Japan Co., Ltd. ★ <b>Katsutomo WAKABAYASHI</b> Fujikura Kasei Co., Ltd.	<b>FPD Materials &amp; Components</b> ★ <b>Keltaro KONDO</b> HOYA CORPORATION ★ <b>Shohel MIYAZAKI</b> SK-Electronics CO.,LTD	<i>Congratulations!</i>	



**THANK YOU**

**STANDARDS**